

## **Integrated Packaging of Multiple Double Sided Cooling Planar Bond Power Modules**

### **Disclosure Number**

201303211

### **Technology Summary**

The invention relates to power electronics and more specifically to a power inverter with improved performance. The content of any power module packaging technology includes structure, materials and processing techniques. The inverter is composed of three planar power packages. The three power packages are assembled together by special coolant manifolds. The final package will features enormous advancement in performance parameters, leading to huge improvement in cost reduction, power density increase, reliability enhancement and cost-effective manufacturability.

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